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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10036389	FILING DATE 01/07/2002	CLASS 257	SUBCLASS	GAU 2811	EXAMINER
**APPLICANTS: Liu Cheng-Yi; Swan Johanna; Towle Steven;					
**CONTINUING DATA VERIFIED: <i>none just</i>					
<p>BEST AVAILABLE COPY</p>					
**FOREIGN APPLICATIONS VERIFIED: <i>none just</i>					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials		2207/12660			
TITLE : Thinned die integrated circuit package					

U.S. DEPT. OF COMM /PAT. & TM-PTO-435L (Rev. 12-95)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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